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L1 ANSWER 1 OF 1 WPIDS COPYRIGHT 1997 DERWENT INFORMATION LTD
 AN 93-012571 [02] WPIDS
 TI Surround circuit for delaying digital signal by utilising RAM -
 reduces delayed RAM capacity necessary for surround process, thus
 reduces digital signal process and delayed RAM up to its formable
 level on same chip NoAbstract.
 DC T01 U22 W04
 PA (NIDE) NEC CORP
 CYC 1
 PI JP 04339500 A 921126 (9302)* 4 pp H04S005-02 <--
 ADT JP 04339500 A JP 91-111364 910516
 PRAI JP 91-111364 910516
 IC ICM H04S005-02
 ICS H03H017-02; H04S001-00
 FS EPI
 FA NOAB; GI
 MC EPI: T01-J08B; U22-G01D; W04-R01C5; W04-R05

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L2 1 JP04339500/PN

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L2 ANSWER 1 OF 1 JAPIO COPYRIGHT 1997 JPO and Japio
 AN 92-339500 JAPIO
 TI SURROUNDING CIRCUIT
 IN YAZAWA AKIRA
 PA NEC CORP, JP (CO 000423)
 PI JP 04339500 A 19921126 Heisei
 AI JP 91-111364 (JP03111364 Heisei) 19910516
 SO PATENT ABSTRACTS OF JAPAN, Unexamined Applications, Section: E,
 Sect. No. 1350, Vol. 17, No. 192, P. 124 (19930414)
 IC ICM (5) H04S005-02
 ICS (5) H03H017-02; (5) H04S001-00
 ICA (5) G10K015-12
 CC 42.5 ELECTRON - Applied electronic equipment
 44.1 COMMUNICATION - Transmission circuit and antenna
 CT R104 APPLIED ELECTRONICS - 4 channel stereo
 AB PURPOSE: To faithfully reproduce the surrounding sound by writing a
 down-sampling signal of a sampling frequency in a delay RAM, and
 reading out the sampling frequency by executing over-sampling.
 CONSTITUTION: An audio input signal, is inputted to a digital signal
 processing circuit, its sampling frequency is lowered by a
 down-sampling converter, and it is written in a delay RAM. As a
 result, the written data quantity is reduced. Also, data read out of
 the delay RAM is subjected to over-sampling in reverse to the time
 of write and returned to its original sampling frequency. As a
 result, the capacity of the delay RAM required for a surrounding
 processing can be reduced, and a digital signal processing and the
 delay RAM can be lowered to a level in which they can be formed on

the same chip. In such a way, a surrounding sound can be reproduced faithfully.

additional element is controlled at 0.005-1.0%. The grain size of the alloy is pref. adjusted to 0.015 mm or less by final annealing. The annealed alloy may be cold rolled with a work ratio of 3-20%.

USE/ADVANTAGE - Useful as structural material of a heat exchanger, e.g. a steam condenser, a water heater or a cooler. The corrosion resistance of the alloy material esp. at its welded part is improved by the addition of Sn, Al and As or Sb. The corrosion resistance is further enhanced by making the grain size smaller. The addn. elements such as B, Ni, Si, etc. improve the mechanical strength of the alloy without reducing the corrosion resistance.

0/2

FS CPI

FA AB

MC CPI: M26-B03; M26-B03A; M26-B03T; M26-B03Z

L2 ANSWER 6 OF 6 WPIDS COPYRIGHT 1997 DERWENT INFORMATION LTD

AN 82-97679E [46] WPIDS

TI Inexpensive copper alloy for electric contacts - contains germanium, antimony or gallium, and can replace costly silver alloys.

DC L03 M26 P53 V03 X13

IN RAUTER, G; SCHULTZ, L; WILLHELM, M

PA (SIEI) SIEMENS AG

CYC 14

PI EP 64181 A 821110 (8246)* DE 15 pp

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R: AT DE FR GB IT NL SE

DE 3116680 A 821118 (8247)

JP 57181348 A 821108 (8250)

NO 8201339 A 821122 (8250)

FI 8200583 A 821231 (8307)

PT 74797 A 830118 (8310)

DK 8201843 A 830314 (8317)

ZA 8202858 A 830124 (8317)

EP 64181 B 850213 (8507) DE

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R: AT BE FR GB IT NL SE

DE 3262286 G 850328 (8514)

ADT EP 64181 A EP 82-103118 820413

PRAI DE 81-3116680 810427

REP 2.Jnl.Ref ; DE 1289991; FR 2294527; FR 2428904; GB 1084351; JP 52020288; JP 52030217

IC B22F003-00; C22C009-00; H01H001-02

AB EP 64181 A UPAB: 930915

The alloy is used esp. for low voltage switches, and switchgear used in electric wiring systems, and contains Cu with at least one of the elements Sb, Ga, Ge, which are present in atomic percent in the amts. 0.01-7% Sb; 0.5-20% Ga; and 0.5-10% Ge. The alloy may also contain (in atomic %) 0.1-2% Cd; 0.01-0.8% Cr; 0.1-1.8% Co; 0.1-3% Pd; and/or 0.5-10% Si, the amts. of these additional elements should not exceed the amt. of Sb, Ga, and/or Ge present. The esp. pref. alloy contains 3-7 esp. 5% Ge, and is made by melting in an inert gas, then heat-treated at 600-950 deg.C. Alternatively, the alloys may be made by powder metallurgy, the compacts being heated to cause diffusion in the solid state.

The alloy can replace expensive Ag contact alloys.

FS CPI EPI GMPI

FA AB

MC CPI: L03-A01A; L03-B04; M26-B03; M26-B03A; M26-B03S; M26-B03X

EPI: V03-A01; X13-A01

L1 ANSWER 1 OF 5 WPIDS COPYRIGHT 1997 DERWENT INFORMATION LTD

AN 93-012571 [02] WPIDS

TI Surround circuit for delaying digital signal by utilising RAM - reduces delayed RAM capacity necessary for surround process, thus reduces digital signal process and delayed RAM up to its formable level on same chip NoAbstract.